



Electronics

Destructive Physical Analysis (DPA)

Microcircuits–Hybrids



Reference Mil-Std-1580C

Hermetic, Monolithic, Multichip, and Hybrid	in Accordance with
16.1.1.1 External Visual (3 Samples)	Mil STD 883
16.1.1.2 External Prohibited Materials (1 Sample) XRF or SEM/EDX	
16.1.1.3 Hermeticity (not available at this location)	
16.1.1.4 Radiography (3 Samples)	
16.1.1.5 PIND (not available at this location)	
16.1.1.6 RGA (not available at this location)	
16.5.1.5 Decapsulation (3 Samples)	
16.1.1.7 Internal Prohibited Materials (1 Sample) XRF or SEM/EDX	
16.1.1.8 Internal Visual (3 Samples)	Mil STD 883
16.1.1.9 Bond Pull (2 Samples)	
16.1.1.10 SEM (2/monolithic) (1/hybrid)	Mil STD 883
16.1.1.11 Die Shear for Monolithics (2 Samples)	Mil STD 883
16.1.1.12 Passive Element Shear (1 Sample)	Mil STD 883
Photo Documentation and Report	

Plastic Encapsulated Microcircuits	in Accordance with
16.5.1.1 External Visual (3 Samples)	Mil STD 883
16.5.1.1.2 External Prohibited Materials (1 Sample) XRF or SEM/EDX	
16.5.1.2 Radiography (3 Samples)	Mil STD 883
16.5.1.3 Acoustic Microscopy (3 Samples)	J-STD-035
16.5.1.4 Cross Section (1 Sample)	
16.5.1.5 Decapsulation (2 Samples)	
16.5.1.6 Internal Visual (2 Samples)	
16.5.1.7 Wire Bond Shear Test (2 Samples)	JESD-STD-B116
16.5.1.8 Bond Pull (2 Samples up to 20 wires per device)	Mil STD 883
16.5.1.9 Glassivation Integrity (1 Sample)	Mil STD 883
16.5.1.10 SEM (1 Sample)	Mil STD 883
Photo Documentation and Report	

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